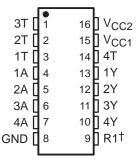
SLLS083B - NOVEMBER 1970 - REVISED MAY 1995

- Meets or Exceeds the Requirements of ANSI Standard EIA/TIA-232-E and ITU Recommendation V.28
- Input Resistance . . . 3 k $\Omega$  to 7 k $\Omega$  Over Full EIA/TIA-232-E Voltage Range
- Input Threshold Adjustable to Meet Fail-Safe Requirements Without Using External Components
- Built-In Hysteresis for Increased Noise Immunity
- Inverting Output Compatible With TTL
- Output With Active Pullup for Symmetrical Switching Speeds
- Standard Supply Voltages . . . 5 V or 12 V

### D OR N PACKAGE (TOP VIEW)



† For function of R1, see schematic

### description

The SN75154 is a monolithic low-power Schottky line receiver designed to satisfy the requirements of the standard interface between data terminal equipment and data communication equipment as defined by ANSI Standard EIA/TIA-232-E. Other applications are for relatively short, single-line, point-to-point data transmission and for level translators. Operation is normally from a single 5-V supply; however, a built-in option allows operation from a 12-V supply without the use of additional components. The output is compatible with most TTL circuits when either supply voltage is used.

In normal operation, the threshold-control terminals are connected to the  $V_{CC1}$  terminal, even if power is being supplied via the alternate  $V_{CC2}$  terminal. This provides a wide hysteresis loop, which is the difference between the positive-going and negative-going threshold voltages. See typical characteristics. In this mode of operation, if the input voltage goes to zero, the output voltage will remain at the low or high level as determined by the previous input.

For fail-safe operation, the threshold-control terminals are open. This reduces the hysteresis loop by causing the negative-going threshold voltage to be above zero. The positive-going threshold voltage remains above zero as it is unaffected by the disposition of the threshold terminals. In the fail-safe mode, if the input voltage goes to zero or an open-circuit condition, the output will go to the high level regardless of the previous input condition.

The SN75154 is characterized for operation from 0°C to 70°C.



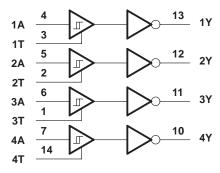
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



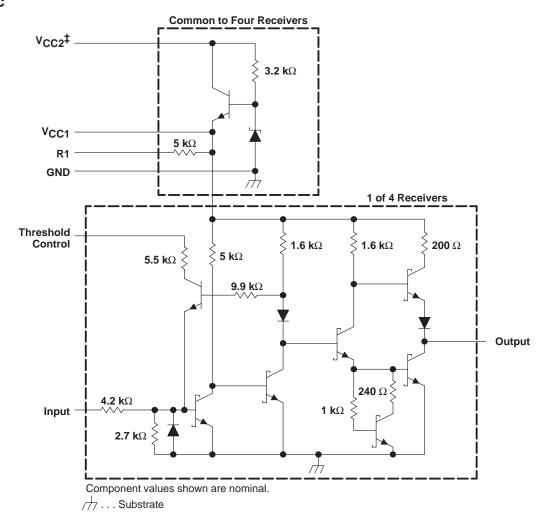
### logic symbol†

#### 1A 13 1T THRS ADJ 5 2A 12 2 2Y **2T** 6 3A 11 **3Y 3T** 7 4A 10 4Y 14 4T

### logic diagram (positive logic)



### schematic



<sup>&</sup>lt;sup>‡</sup> When V<sub>CC1</sub> is used, V<sub>CC2</sub> may be left open or shorted to V<sub>CC1</sub>. When V<sub>CC2</sub> is used, V<sub>CC1</sub> must be left open or connected to the threshold control pins.



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Normal sup	ply voltage, V <sub>CC1</sub> (see Note 1)	 7 V
Input voltag	e, V <sub>I</sub>	 ±25 V
Continuous	total power dissipation	 See Dissipation Rating Table
Operating fr	ree-air temperature range, T <sub>A</sub>	 0°C to 70°C
Storage ten	nperature range, T <sub>sta</sub>	 –65°C to 150°C
	erature 1.6 mm (1/16 inch) from	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW
N	1150 mW	9.2 mW/°C	736 mW
NS	625 mW	5.0 mW/°C	400 mW

### recommended operating conditions

	MIN	NOM	MAX	UNIT
Normal supply voltage, V <sub>CC1</sub>	4.5	5	5.5	V
Alternate supply voltage, V <sub>CC2</sub>	10.8	12	13.2	V
High-level input voltage, VIH (see Note 2)	3		15	V
Low-level input voltage, V <sub>IL</sub> (see Note 2)	-15		-3	V
High-level output current, IOH			-400	μΑ
Low-level output current, IOL			16	mA
Operating free-air temperature, T <sub>A</sub>	0		70	°C

NOTE 2: The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for logic and threshold levels only, e.g., when 0 V is the maximum, the minimum limit is a more negative voltage.



NOTE 1: Voltage values are with respect to network GND terminal.

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST FIGURE	TEST COND	ITIONS	MIN	TYP	MAX	UNIT
\/	Positive-going input	Normal operation	1			0.8	2.2	3	V
V <sub>IT+</sub>	threshold voltage	Fail-safe operation	'			0.8	2.2	3	V
\/	Negative-going input	Normal operation	1			-3	-1.1	0	V
VIT-	threshold voltage	Fail-safe operation	'			0.8	1.4	3	V
\/.	Hysteresis voltage	Normal operation	1			0.8	3.3	6	V
V <sub>hys</sub>	$(V_{IT+} - V_{IT-})$					0	0.8	2.2	V
Vон	High-level output voltage		1	$I_{OH} = -400  \mu A$	2.4	3.5		V	
VOL	Low-level output voltage		1	I <sub>OL</sub> = 16 mA		0.29	0.4	V	
				$\Delta V_{\parallel} = -25 \text{ V to } -16$	4 V	3	5	7	
				$\Delta V_{ } = -14 \text{ V to } -3$	3	5	7		
rį	Input resistance		2	$\Delta V_{I} = -3 \text{ V to } 3 \text{ V}$		3	6	8	kΩ
				$\Delta V_I = 3 V \text{ to } 14 V$		3	5	7	Naz
				$\Delta V_{\parallel}$ = 14 V to 25 V	'	3	5	7	
V <sub>I(open)</sub>	Open-circuit input voltage		3	I <sub>I</sub> = 0		0	0.2	2	V
los	Short-circuit output current‡		4	$V_{CC1} = 5.5 \text{ V},$	$V_{I} = -5 V$	-10	-20	-40	mA
I <sub>CC1</sub>	Supply current from V <sub>CC1</sub>		5	$V_{CC1} = 5.5 \text{ V},$	T <sub>A</sub> = 25°C		20	35	mΛ
I <sub>CC2</sub>	Supply current from V <sub>CC2</sub>		٦	$V_{CC2} = 13.2 \text{ V},$	T <sub>A</sub> = 25°C		23	40	mA

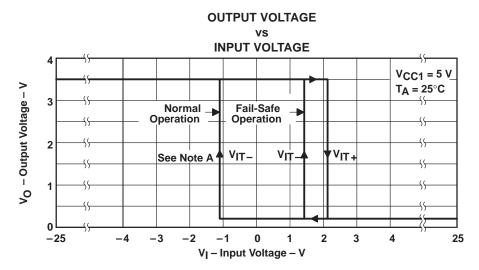
# switching characteristics, $V_{CC1}$ = 5 V, $T_{A}$ = 25°C, N = 10

	PARAMETER	TEST FIGURE	TEST COM	NDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output					11		ns
tPHL	Propagation delay time, high- to low-level output	6	$C_1 = 50 \text{ pF},$	$R_1 = 390 \Omega$		8		ns
tTLH	Transition time, low- to high-level output	b	CL = 50 pr,	KL = 390 12		7		ns
tTHL	Transition time, high- to low-level output					2.2		ns



<sup>†</sup> All typical values are at V<sub>CC1</sub> = 5 V, T<sub>A</sub> = 25°C. ‡ Not more than one output should be shorted at a time.

### **TYPICAL CHARACTERISTICS**



NOTE A: For normal operation, the threshold controls are connected to  $V_{\rm CC1}$ . For fail-safe operation, the threshold controls are open.

Figure 1

### PARAMETER MEASUREMENT INFORMATION

### dc test circuits†

#### **TEST TABLE**

TEST	MEASURE	Α	Т	Y	V <sub>CC1</sub>	V <sub>CC2</sub>
Open circuit input (fail agfa)	Voн	Open	Open	IOH	4.5 V	Open
Open-circuit input (fail safe)	Voн	Open	Open	loh	Open	10.8 V
View min View min (fail acta)	Voн	0.8 V	Open	IOH	5.5 V	Open
V <sub>IT+</sub> min, V <sub>IT-</sub> min (fail safe)	VOH	0.8 V	Open	IOH	Open	13.2 V
/ <sub>IT+</sub> min (normal)	Voн	Note A	V <sub>CC1</sub>	IOH	5.5 V and T	Open
	Voн	Note A	V <sub>CC1</sub>	IOH	Т	13.2 V
Viii may Vi= min (normal)	Voн	-3 V	V <sub>CC1</sub>	I <sub>OH</sub>	5.5 V and T	Open
V <sub>IL</sub> max, V <sub>IT+</sub> min (normal)	Voн	-3 V	V <sub>CC1</sub>	I <sub>OH</sub>	Т	13.2 V
Vullmin Vie may Vie may (fail acts)	VOL	3 V	Open	loL	4.5 V	Open
V <sub>IH</sub> min, V <sub>IT+</sub> max, V <sub>IT-</sub> max (fail safe)	VOL	3 V	Open	loL	Open	10.8 V
Vullmin Vim may (normal)	VOL	3 V	V <sub>CC1</sub>	loL	4.5 V and T	Open
V <sub>IH</sub> min, V <sub>IT+</sub> max (normal)	VOL	3 V	V <sub>CC1</sub>	loL	Т	10.8 V
View may (normal)	VoL	Note B	VCC1	loL	5.5 V and T	Open
V <sub>IT</sub> max (normal)	VOL	Note B	V <sub>CC1</sub>	loL	Т	13.2 V

NOTES: A. Momentarily apply -5 V, then 0.8 V.

B. Momentarily apply 5 V, then GND.

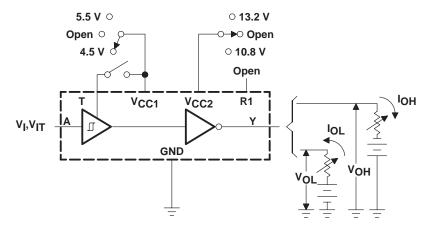
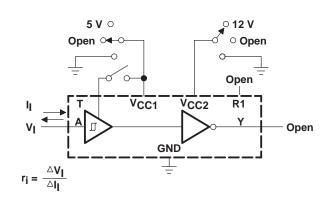


Figure 2. V<sub>IH</sub>, V<sub>IL</sub>, V<sub>IT+</sub>, V<sub>IT-</sub>, V<sub>OH</sub>, V<sub>OL</sub>

<sup>†</sup> Arrows indicate actual direction of current flow. Current into a terminal is a positive value.

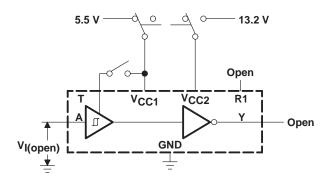
### PARAMETER MEASUREMENT INFORMATION

## dc test circuits† (continued)



	TEST TABLE									
Т	V <sub>CC1</sub>	V <sub>CC2</sub>								
Open	5 V	Open								
Open	GND	Open								
Open	Open	Open								
V <sub>CC1</sub>	T and 5 V	Open								
GND	GND	Open								
Open	Open	12 V								
Open	Open	GND								
V <sub>CC1</sub>	Т	12 V								
V <sub>CC1</sub>	Т	GND								
VCC1	Т	Open								

Figure 3. Input Resistance



 TEST TABLE

 T
 VCC1
 VCC2

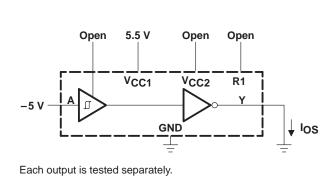
 Open
 5.5 V
 Open

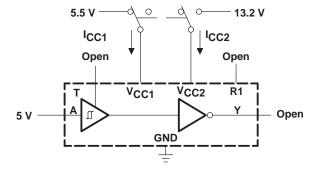
 VCC1
 5.5 V
 Open

 Open
 Open
 13.2 V

 VCC1
 T
 13.2 V

Figure 4. Input Voltage (Open)





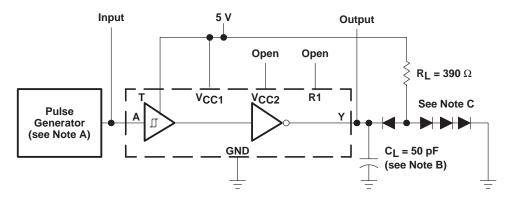
All four line receivers are tested simultaneously.

Figure 5. Output Short-Circuit Current

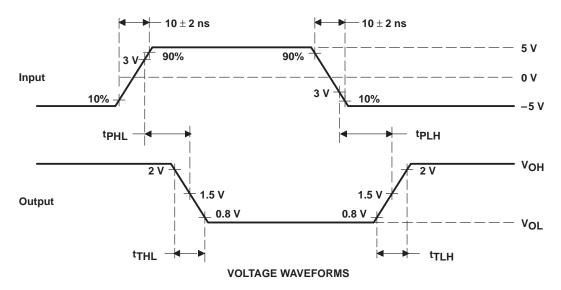
Figure 6. Supply Current

<sup>&</sup>lt;sup>†</sup> Arrows indicate actual direction of current flow. Current into a terminal is a positive value.

### PARAMETER MEASUREMENT INFORMATION



**TEST CIRCUIT** 



NOTES: A. The pulse generator has the following characteristics:  $Z_O$  = 50  $\Omega$ ,  $t_W \le 200$  ns, duty cycle  $\le 20\%$ .

- B. C<sub>L</sub> includes probe and jig capacitance.
- C. All diodes are 1N3064.

Figure 6. Test Circuit and Voltage Waveforms





10-Jun-2014

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN75154D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	(3) Level-1-260C-UNLIM	0 to 70	SN75154	Samples
SN75154DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75154	Samples
SN75154DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75154	Samples
SN75154DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75154	Samples
SN75154N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75154N	Samples
SN75154NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75154N	Samples
SN75154NSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75154	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



### PACKAGE OPTION ADDENDUM

10-Jun-2014

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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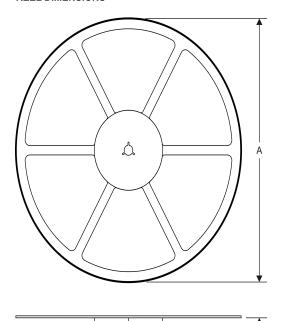
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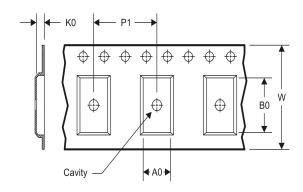
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### TAPE AND REEL INFORMATION

### **REEL DIMENSIONS**



### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TAPE AND REEL INFORMATION

\*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75154DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75154NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75154DR	SOIC	D	16	2500	333.2	345.9	28.6
SN75154NSR	SO	NS	16	2000	367.0	367.0	38.0

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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